

Electronic Patent Application Fee Transmittal

Application Number:	10830188			
Filing Date:	21-Apr-2004			
Title of Invention:	Method for accommodating small minimum die in wire bonded area array packages			
First Named Inventor/Applicant Name:	Ryan Lane			
Filer:	William M. Hooks/Sheryl Schoen			
Attorney Docket Number:	020378D1			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 5 months with \$0 paid	1255	1	2350	2350

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				2350